

## 30V P-Channel Enhancement Mode MOSFET

### Description

The NP20P03D6 G uses advanced trench technology to provide excellent  $R_{DS(ON)}$ . This device is suitable for use as a load switch or in PWM applications.

### General Features

- ◆  $V_{DS} = -30V$   $I_D = -20A$   
 $R_{DS(ON)}(Typ.) = 16m\Omega$  @  $V_{GS} = -10V$   
 $R_{DS(ON)}(Typ.) = 21m\Omega$  @  $V_{GS} = -4.5V$
- ◆ High power and current handing capability
- ◆ Lead free product is acquired
- ◆ Surface mount package
- ◆ 150 °C operating temperature
- ◆ 100% UIS tested

### Application

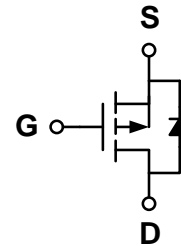
- ◆ PWM applications
- ◆ Load switch
- ◆ Uninterruptible power supply

### Package

- ◆ PDFN5\*6-8L-A

*100% UIS TESTED!*  
*100%  $\Delta V_{ds}$  TESTED!*

### Schematic diagram

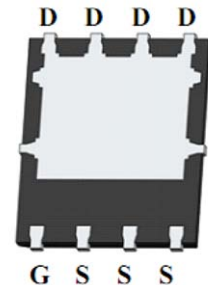


### Marking and pin assignment

PDFN5\*6-8L-A



Top View



Bottom View

XXXXX—Wafer Information  
 YYYYY—Quality Code



### Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
NP20P03D6-G	-55°C to +150°C	PDFN5*6-8L-A	5000

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

parameter	symbol	limit	unit
Drain-source voltage	$V_{DS}$	-30	V
Gate-source voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	TC=25°C	20
		TC=70°C	16
Pulsed Drain Current	$I_{DP}$	80	A
Avalanche energy (Tj=25°C, VDD=30V, VG=10V, L=0.5mH, Rg=25Ω)	$E_{AS}$	170	mJ
Power Dissipation	$P_D$	TC=25°C	31
		TC=70°C	15
Operating junction Temperature range	Tj	-55—150	°C

**Electrical Characteristics** (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$	-	-	1	$\mu A$
		$T_J=85^\circ C$	-	-	30	
Gate Leakage Current	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.2	-1.6	-2.5	V
Drain-source on-state resistance <sup>1</sup>	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-20A$	-	16	21	m $\Omega$
		$V_{GS}=-4.5V, I_D=-15A$	-	21	26	
On Status Drain Current	$I_{D(on)}$	$V_{DS}=-15V, V_{GS}=-10V$	25	-	-	A
<b>Diode Characteristics</b>						
Diode Forward Voltage <sup>1</sup>	$V_{SD}$	$I_{SD}=-20A, V_{GS}=0V$	-	-0.8	-1.3	V
Diode Continuous Forward Current	$I_S$		-	-25	-	A
Reverse Recovery Time	$t_{rr}$	$I_F=-20A,$ $di/dt=-100A/\mu s$	-	24	-	ns
Reverse Recovery Charge	$Q_{rr}$		-	16	-	nC
<b>Dynamic Characteristics<sup>2</sup></b>						
Gate Resistance	$R_G$	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	-	0.65	-	$\Omega$
Input capacitance	$C_{ISS}$	$V_{GS}=0V, V_{DS}=-15V$ $f=1.0MHz$	-	1360	-	$\mu F$
Output capacitance	$C_{OSS}$		-	250	-	
Reverse transfer capacitance	$C_{RSS}$		-	210	-	
Turn-on delay time	$t_{D(on)}$	$V_{GS}=-10V, V_{DD}=-30V,$ $R_L=3\Omega, I_D=20A, R_G=2.5\Omega$	-	9	-	ns
Turn-on Rise time	$t_r$		-	10	-	
Turn-off delay time	$t_{D(off)}$		-	50	-	
Turn-off Fall time	$t_f$		-	20	-	
Total gate charge	$Q_g$	$V_{GS}=-10V, I_D=-20A$ $V_{DS}=-15V$	-	31	-	nC
Gate-source charge	$Q_{gs}$		-	3	-	
Gate-drain charge	$Q_{gd}$		-	9	-	

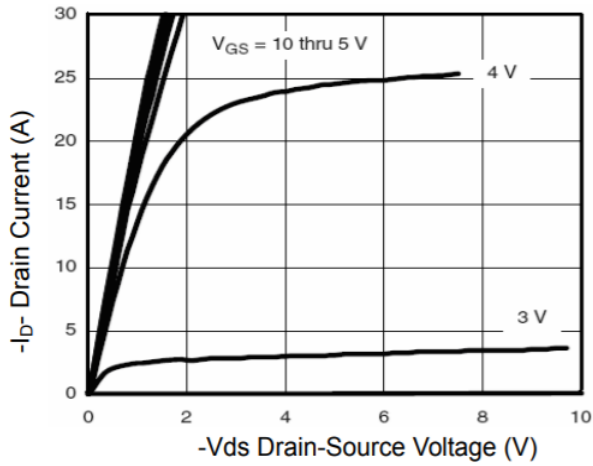
**Thermal Characteristics**

Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient <sup>A</sup>	$\leq 10s$	29	34	$^\circ C/W$
Maximum Junction-to-Ambient <sup>A</sup>	Steady-State			
Maximum Junction-to-Lead <sup>B</sup>	Steady-State	3.2	4	

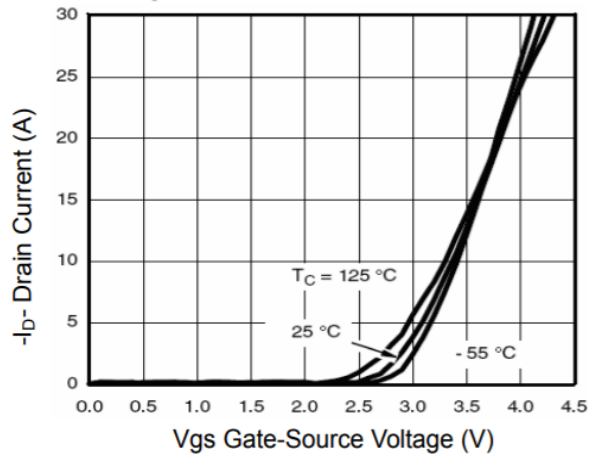
A: The value of  $R_{qJA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ . The value in any given application depends on the user's specific board design. The current rating is based on the  $t \leq 10s$  thermal resistance rating.

B: The  $R_{qJA}$  is the sum of the thermal impedance from junction to lead  $R_{qJL}$  and lead to ambient.

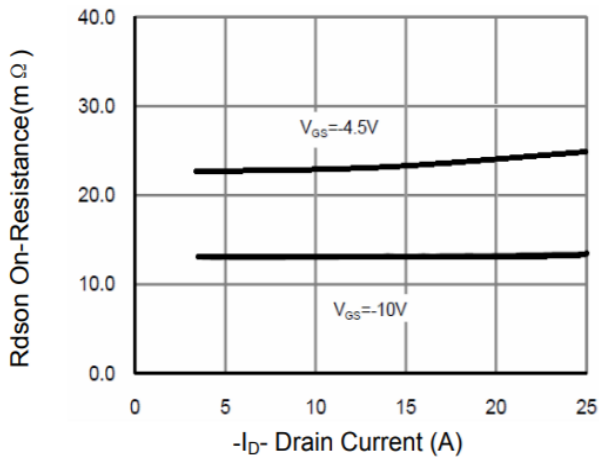
## Typical Performance Characteristics



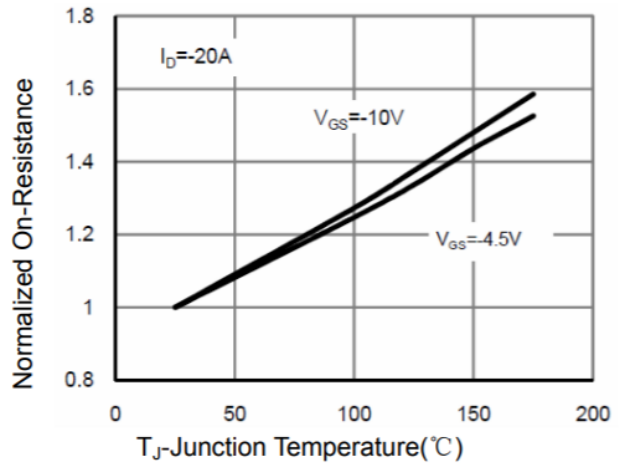
**Figure 1 Output Characteristics**



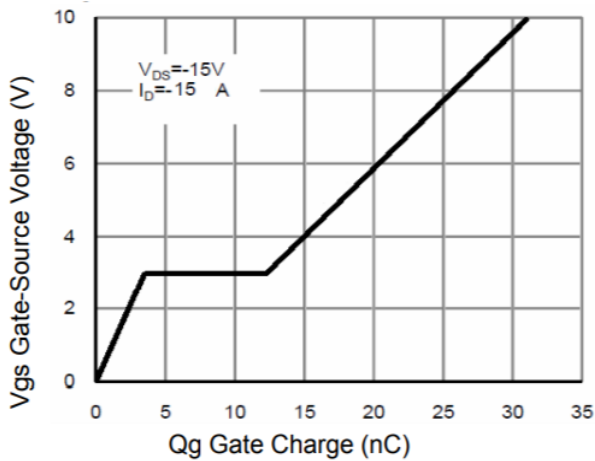
**Figure 2 Transfer Characteristics**



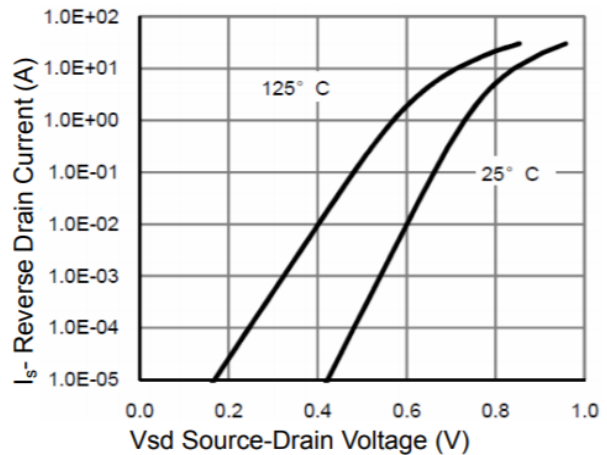
**Figure 3 Rdson- Drain Current**



**Figure 4 Rdson-Junction Temperature**



**Figure 5 Gate Charge**



**Figure 6 Source- Drain Diode Forward**

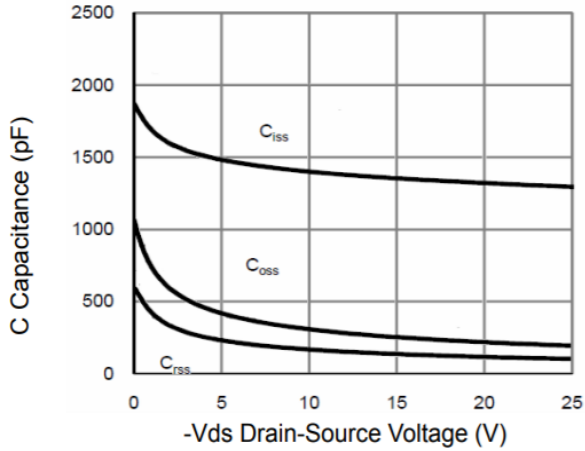


Figure 7 Capacitance vs Vds

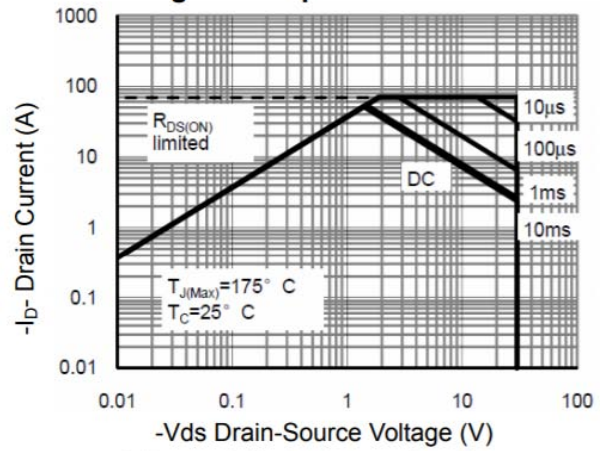


Figure 8 Safe Operation Area

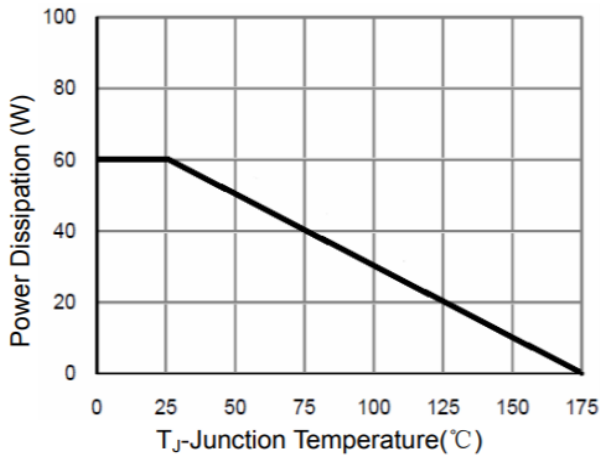


Figure 9 Power De-rating

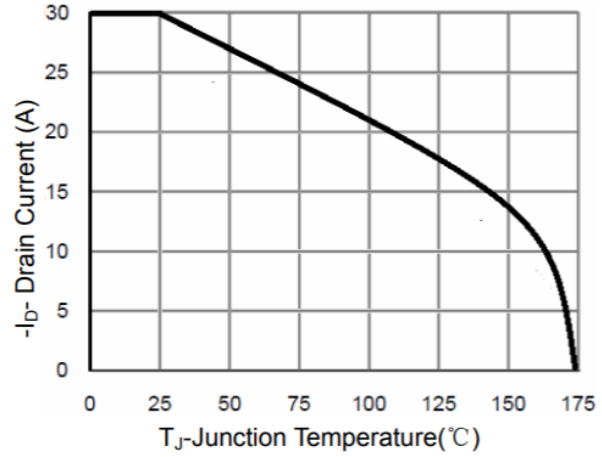


Figure 10 ID Current Derating

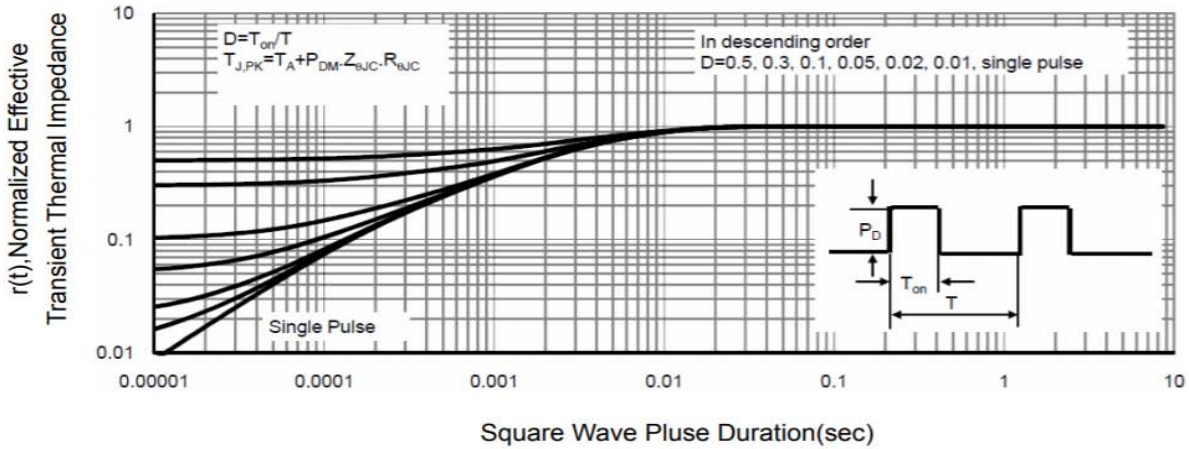


Figure 11 Normalized Maximum Transient Thermal Impedance

Figure A: Gate Charge Test Circuit & Waveforms

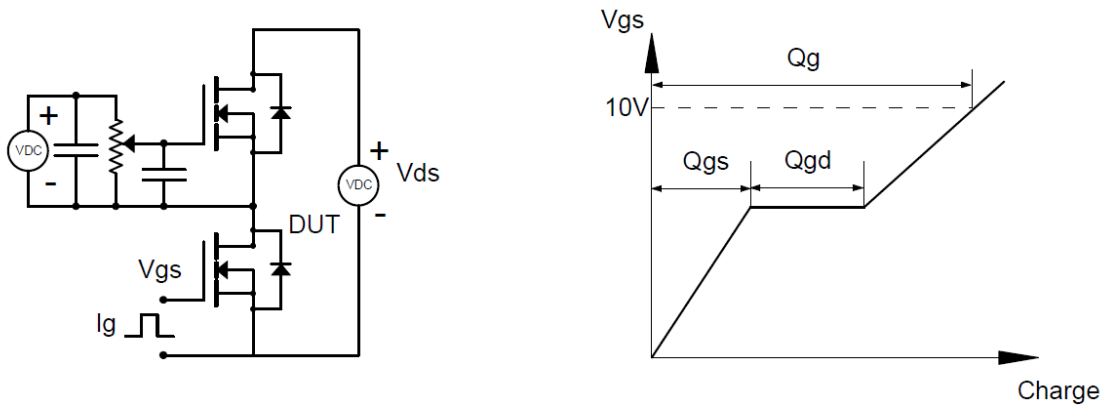


Figure B: Resistive Switching Test Circuit & Waveforms

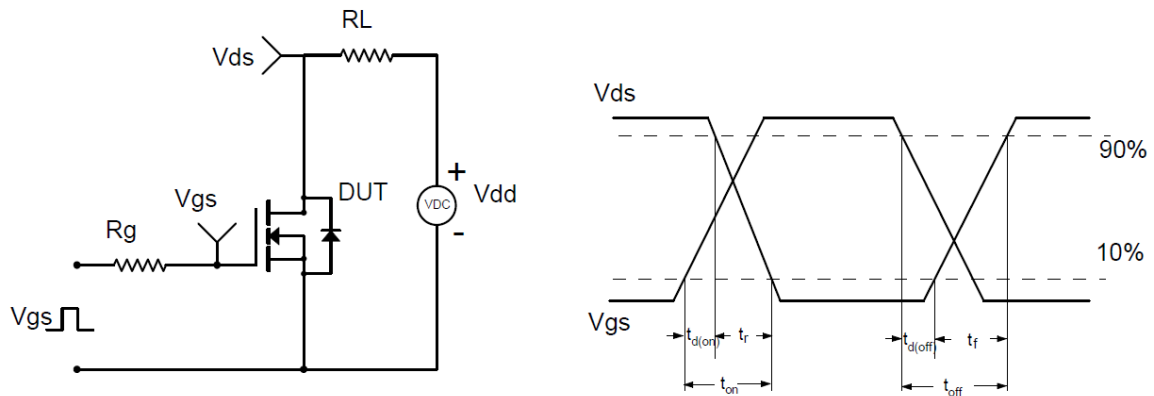


Figure C: Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

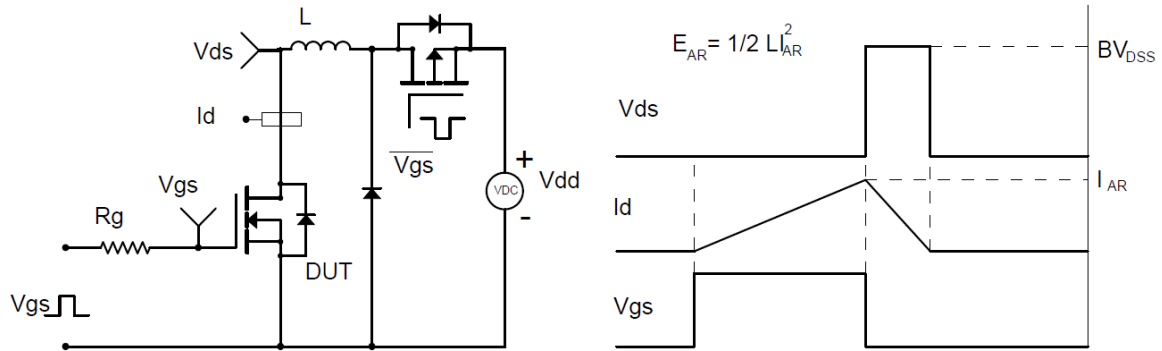
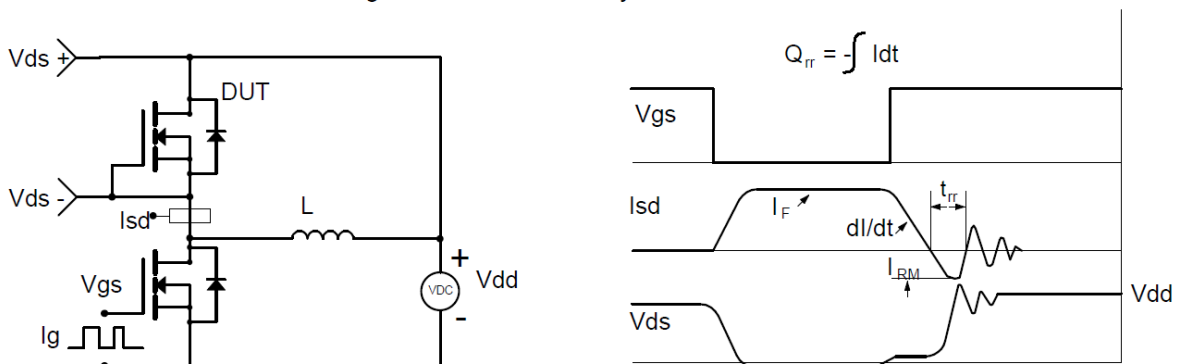
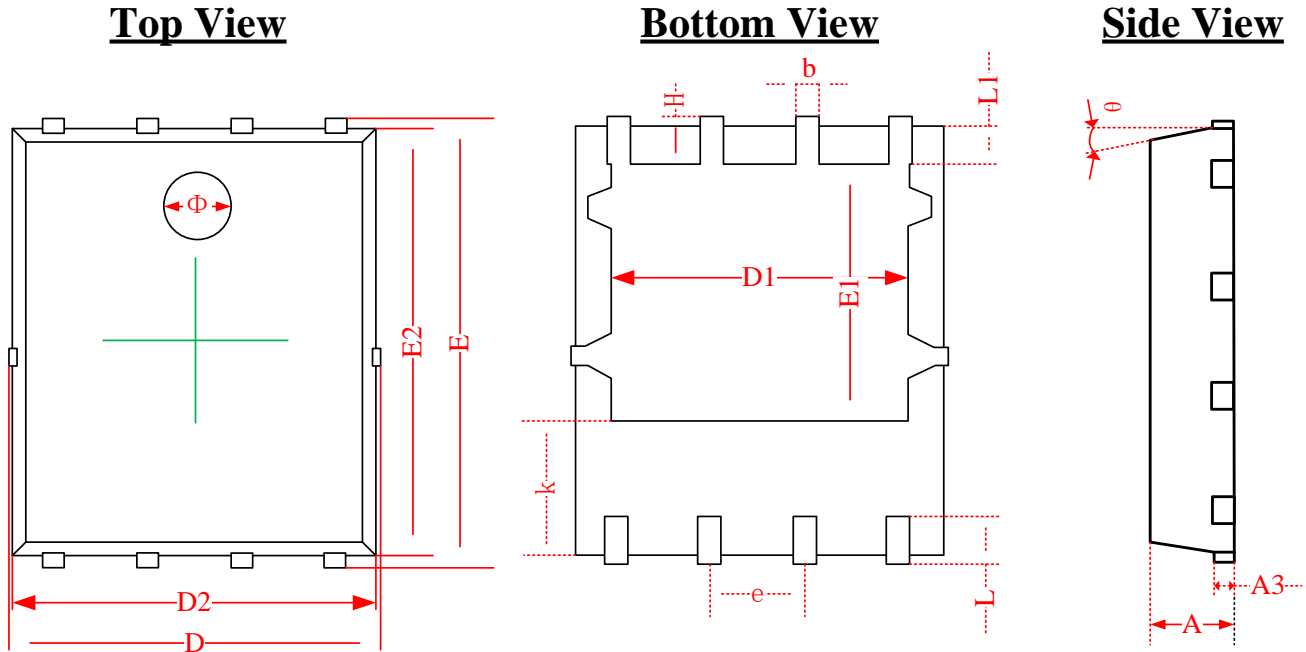


Figure D: Diode Recovery Test Circuit & Waveforms



## Package Information

- PDFN5\*6-8L-A



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.870	0.900	0.930	0.034	0.035	0.036
A3	0.152REF.			0.006REF.		
D	4.944	5.020	5.096	0.195	0.198	0.201
E	5.974	6.050	6.126	0.235	0.238	0.241
D1	3.910	4.010	4.110	0.154	0.158	0.162
E1	3.375	3.475	3.575	0.133	0.137	0.141
D2	4.870	4.900	4.930	0.192	0.193	0.194
E2	5.720	5.750	5.780	0.226	0.227	0.228
k	1.190	1.290	1.390	0.047	0.051	0.055
b	0.350	0.380	0.410	0.014	0.015	0.016
e	1.270TYP.			0.050TYP.		
L	0.559	0.635	0.711	0.022	0.025	0.028
L1	0.424	0.500	0.576	0.017	0.020	0.023
H	0.574	0.650	0.726	0.023	0.026	0.029
$\theta$	10°	11°	12°	10°	11°	12°
$\Phi$	1.150	1.200	1.250	0.045	0.047	0.049